


SIZE	QTY	SYM	PLTD
40	23	X	PLTD
35	3	T	PLTD
55	5	U	PLTD
15	152	V	PLTD
94	6	W	PLTD
125	4	X	PLTD
70	2	Y	NPLTD
205	4	Z	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC)
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK
5. ALL DIMENSIONS ARE IN INCHES

- ART01 = LAYER 1 (COMPONENT SIDE)
- ART02 = LAYER 2 (GND & VOUT)
- ART03 = LAYER 3 (GND)
- ART04 = LAYER 4 (SOLDER SIDE)

Fabrication Drawing

APPROVALS		 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
DRAWN	INIT	DATE	
CHECK			
DESIGN			
ENGR			
TITLE:		Intel's Notebook Processor Power Supply	
SIZE	DEM BRD	LTC3714EG	DC371
A	A		REV. A
SCALE = NONE		DES- SHT 1 of 1	